



HYSOL® EO1090

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PRODUCT DESCRIPTION

Hysol® EO1090 was developed as a one component encapsulant to achieve the maximum reliability performance on COB, BGA, HIC using the specially formulated epoxy resin systems. Storage can be 5-20°C for many months. It is UL94HB equivalent.

PROPERTIES OF UNCURED MATERIAL

Color	Black
Shelf Life @ 4°C, months,	6
Typical Value	
Viscosity @ 25°C, (77°F) (ASTM D2393)	60,000

PHYSICAL PROPERTIES, CURED MATERIAL

Color	Black
Coefficient of Linear Thermal Expansion, In/in/°C, (120°C maximum), ASTM D3386	45×10^{-6}
Thermal Conductivity	9.4×10^{-4}
Glass Transition, Tg, °C, minimum, ASTM D3386	120
Hardness, Shore D, minimum ASTM D2240	95
Specific Gravity, ASTM D792	1.5

Cured Electrical Properties

Dielectric Constant by ASTM D150 @ 25°C, 1kHz	4.2
Dielectric Insulation, @ 25°C, 1kHz	0.0084

Handling

Gel Time, @ 121°C, minutes	8
@ 100°C, minutes	20

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be selected as a sealant for chlorine or their strong oxidizing materials

Cure Schedule

Recommended Cure (For normal Devices)	2-3 hours @ 100°C plus 4-6 hours @ 120°C or 2-3 hours @ 100°C plus 2 hours @ 150°C
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Alternate Cure (Low Stress)	4-6 hours @ 110°C plus 1 hour @ 150°C
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Use suggested cure schedules as general guidelines; other cure schedules may yield satisfactory results.

Note

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Loctite Electronics

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